

BCD-to-Seven Segment Latch/Decoder/Driver

MC14511B

The MC14511B BCD-to-seven segment latch/decoder/driver is constructed with complementary MOS (CMOS) enhancement mode devices and NPN bipolar output drivers in a single monolithic structure. The circuit provides the functions of a 4-bit storage latch, an 8421 BCD-to-seven segment decoder, and an output drive capability. Lamp test ($\overline{\rm LT}$), blanking ($\overline{\rm BI}$), and latch enable (LE) inputs are used to test the display, to turn-off or pulse modulate the brightness of the display, and to store a BCD code, respectively. It can be used with seven-segment light-emitting diodes (LED), incandescent, fluorescent, gas discharge, or liquid crystal readouts either directly or indirectly.

Applications include instrument (e.g., counter, DVM, etc.) display driver, computer/calculator display driver, cockpit display driver, and various clock, watch, and timer uses.

Features

- Low Logic Circuit Power Dissipation
- High-Current Sourcing Outputs (Up to 25 mA)
- Latch Storage of Code
- Blanking Input
- Lamp Test Provision
- Readout Blanking on all Illegal Input Combinations
- Lamp Intensity Modulation Capability
- Time Share (Multiplexing) Facility
- Supply Voltage Range = 3.0 V to 18 V
- Capable of Driving Two Low-power TTL Loads, One Low-power Schottky TTL Load, or Two HTL Loads Over the Rated Temperature Range
- Chip Complexity: 216 FETs or 54 Equivalent Gates
- Triple Diode Protection on all Inputs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 1)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in}	Input Voltage Range, All Inputs	-0.5 to V _{DD} + 0.5	٧
ı	DC Current Drain per Input Pin	10	mA
P_{D}	Power Dissipation, per Package (Note 2)	500	mW
T_A	Operating Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
I _{OHmax}	Maximum Output Drive Current (Source) per Output	25	mA
P _{OHmax}	Maximum Continuous Output Power (Source) per Output (Note 3)	50	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

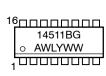
- 1. Maximum Ratings are those values beyond which damage to the device may occur.
- 2. Temperature Derating: "D/DW" Packages: -7.0 mW/°C From 65°C to 125°C
- 3. $P_{OHmax} = I_{OH} (V_{DD} V_{OH})$

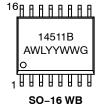




D SUFFIX DW SUFFIX
CASE 751B CASE 751G

MARKING DIAGRAMS





SOIC-16

A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Package

ORDERING INFORMATION

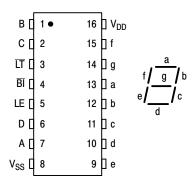
See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

This device contains protection circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit. A destructive high current mode may occur if V_{in} and V_{out} are not constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

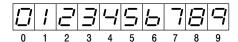
Due to the sourcing capability of this circuit, damage can occur to the device if V_{DD} is applied, and the outputs are shorted to V_{SS} and are at a logical 1 (See Maximum Ratings).

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}).

PIN ASSIGNMENT



DISPLAY



TRUTH TABLE

			Inp	uts							Ou	tputs	3	
LE	BI	LT	D	С	В	Α	а	b	С	d	е	f	g	Display
Х	Х	0	Х	Χ	Χ	Χ	1	1	1	1	1	1	1	8
Х	0	1	Х	Χ	Χ	Χ	0	0	0	0	0	0	0	Blank
0 0 0 0	1 1 1	1 1 1	0 0 0 0	0 0 0	0 0 1 1	0 1 0 1	1 0 1 1	1 1 1 1	1 1 0 1	1 0 1 1	1 0 1 0	1 0 0 0	0 0 1 1	0 1 2 3
0 0 0 0	1 1 1	1 1 1	0 0 0 0	1 1 1	0 0 1 1	0 1 0 1	0 1 0 1	1 0 0 1	1 1 1 1	0 1 1 0	0 0 1 0	1 1 1 0	1 1 1 0	4 5 6 7
0 0 0 0	1 1 1	1 1 1	1 1 1	0 0 0 0	0 0 1 1	0 1 0 1	1 1 0 0	1 1 0 0	1 1 0 0	1 0 0 0	1 0 0 0	1 1 0 0	1 1 0 0	8 9 Blank Blank
0 0 0 0	1 1 1	1 1 1	1 1 1	1 1 1 1	0 0 1 1	0 1 0 1	0 0 0 0	Blank Blank Blank Blank						
1	1	1	Χ	Х	Х	Х				*				*

X = Don't Care

^{*}Depends upon the BCD code previously applied when LE = 0

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				– 55°C		25°C			125°C		
Characteristic		Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 4)	Max	Min	Max	Unit
Output Voltage "0" V _{in} = V _{DD} or 0	Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD} "1"	Level	V _{OH}	5.0 10 15	4.1 9.1 14.1	- - -	4.1 9.1 14.1	4.57 9.58 14.59	- - -	4.1 9.1 14.1	- - -	Vdc
Input Voltage # "0" (V _O = 3.8 or 0.5 Vdc) (V _O = 8.8 or 1.0 Vdc) (V _O = 13.8 or 1.5 Vdc)	Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
(V _O = 0.5 or 3.8 Vdc) (V _O = 1.0 or 8.8 Vdc) (V _O = 1.5 or 13.8 Vdc)	Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Voltage (I _{OH} = 0 mA) S (I _{OH} = 5.0 mA) (I _{OH} = 10 mA) (I _{OH} = 15 mA) (I _{OH} = 20 mA) (I _{OH} = 25 mA)	ource	V _{OH}	5.0	4.1 - 3.9 - 3.4 -	- - - -	4.1 - 3.9 - 3.4 -	4.57 4.24 4.12 3.94 3.70 3.54	1 1 1 1	4.1 - 3.5 - 3.0 -	- - - -	Vdc
(I _{OH} = 0 mA) (I _{OH} = 5.0 mA) (I _{OH} = 10 mA) (I _{OH} = 15 mA) (I _{OH} = 20 mA) (I _{OH} = 25 mA)			10	9.1 - 9.0 - 8.6 -	- - - - -	9.1 - 9.0 - 8.6 -	9.58 9.26 9.17 9.04 8.90 8.70	- - - -	9.1 - 8.6 - 8.2 -	- - - - -	Vdc
(I _{OH} = 0 mA) (I _{OH} = 5.0 mA) (I _{OH} = 10 mA) (I _{OH} = 15 mA) (I _{OH} = 20 mA) (I _{OH} = 25 mA)			15	14.1 - 14 - 13.6 -	- - - - -	14.1 - 14 - 13.6 -	14.59 14.27 14.18 14.07 13.95 13.70	- - - -	14.1 - 13.6 - 13.2 -	- - - - -	Vdc
Output Drive Current (V _{OL} = 0.4 V) (V _{OL} = 0.5 V) (V _{OL} = 1.5 V)	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		l _{in}	15	-	± 0.1	-	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance		C _{in}	1	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package) V _{in} = 0 or V _D I _{out} = 0 μA)D,	I _{DD}	5.0 10 15		5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Notes 5 & (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, a buffers switching)	,	lτ	5.0 10 15			$I_T = (3$	1.9 μΑ/kHz) f 3.8 μΑ/kHz) f 5.7 μΑ/kHz) f	+ I _{DD}			μAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Noise Margin for both "1" and "0" level =

1.0 Vdc min @ V_{DD} = 5.0 Vdc 2.0 Vdc min @ V_{DD} = 10 Vdc

- 2.5 Vdc min @ V_{DD} = 15 Vdc 5. The formulas given are for the typical characteristics only at 25°C. 6. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + 3.5 \text{ x } 10^{-3} \text{ (}C_L - 50\text{) }V_{DD}f$$

where: I_{T} is in μA (per package), C_{L} in pF, V_{DD} in Vdc, and f in kHz is input frequency.

^{4.} Noise immunity specified for worst-case input combination.

SWITCHING CHARACTERISTICS (Note 7) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C}$)

Characteristic	Symbol	V _{DD} Vdc	Min	Тур	Max	Unit
Output Rise Time $t_{TLH} = (0.40 \text{ ns/pF}) \text{ C}_{L} + 20 \text{ ns} \\ t_{TLH} = (0.25 \text{ ns/pF}) \text{ C}_{L} + 17.5 \text{ ns} \\ t_{TLH} = (0.20 \text{ ns/pF}) \text{ C}_{L} + 15 \text{ ns}$	t _{TLH}	5.0 10 15	- - -	40 30 25	80 60 50	ns
Output Fall Time $t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 50 \text{ ns} \\ t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 37.5 \text{ ns} \\ t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 37.5 \text{ ns}$	t _{THL}	5.0 10 15	- - -	125 75 65	250 150 130	ns
Data Propagation Delay Time $t_{PLH} = (0.40 \text{ ns/pF}) \text{ C}_L + 620 \text{ ns}$ $t_{PLH} = (0.25 \text{ ns/pF}) \text{ C}_L + 237.5 \text{ ns}$ $t_{PLH} = (0.20 \text{ ns/pF}) \text{ C}_L + 165 \text{ ns}$	t _{PLH}	5.0 10 15	- - -	640 250 175	1280 500 350	ns
t_{PHL} = (1.3 ns/pF) C_L + 655 ns t_{PHL} = (0.60 ns/pF) C_L + 260 ns t_{PHL} = (0.35 ns/pF) C_L + 182.5 ns	t _{PHL}	5.0 10 15	- - -	720 290 200	1440 580 400	
	t _{PLH}	5.0 10 15	- - -	600 200 150	750 300 220	ns
t_{PHL} = (0.85 ns/pF) C_L + 442.5 ns t_{PHL} = (0.45 ns/pF) C_L + 177.5 ns t_{PHL} = (0.35 ns/pF) C_L + 142.5 ns	t _{PHL}	5.0 10 15	- - -	485 200 160	970 400 320	
	t _{PLH}	5.0 10 15	- - -	313 125 90	625 250 180	ns
t_{PHL} = (1.3 ns/pF) C_L + 248 ns t_{PHL} = (0.45 ns/pF) C_L + 102.5 ns t_{PHL} = (0.35 ns/pF) C_L + 72.5 ns	t _{PHL}	5.0 10 15	- - -	313 125 90	625 250 180	
Setup Time	t _{su}	5.0 10 15	100 40 30	- - -	- - -	ns
Hold Time	t _h	5.0 10 15	60 40 30	- - -	- - -	ns
Latch Enable Pulse Width	t _{WL}	5.0 10 15	520 220 130	260 110 65	- - -	ns

^{7.} The formulas given are for the typical characteristics only.

Input LE low, and Inputs D, \overline{BI} and \overline{LT} high. f in respect to a system clock. All outputs connected to respective C_L loads.

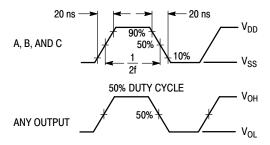
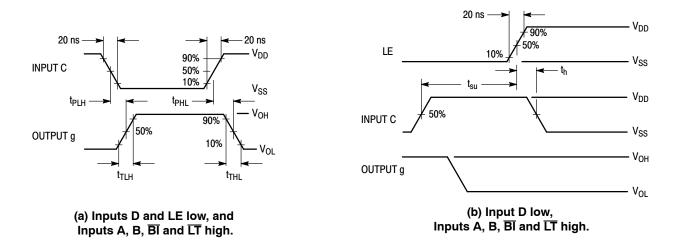
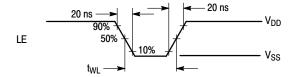


Figure 1. Dynamic Power Dissipation Signal Waveforms



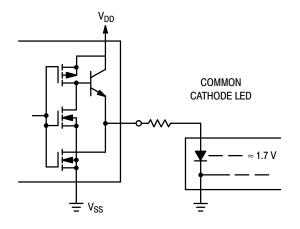


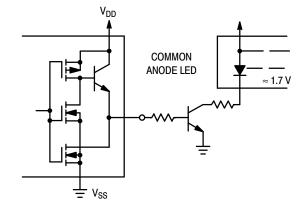
(c) Data DCBA strobed into latches.

Figure 2. Dynamic Signal Waveforms

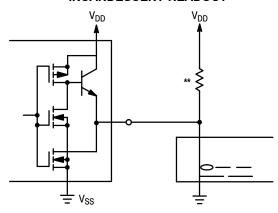
CONNECTIONS TO VARIOUS DISPLAY READOUTS

LIGHT EMITTING DIODE (LED) READOUT

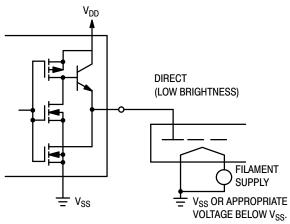




INCANDESCENT READOUT

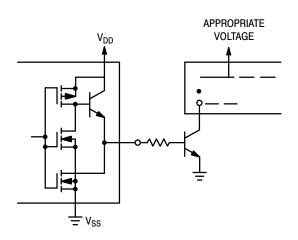


FLUORESCENT READOUT



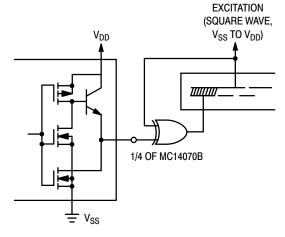
(CAUTION: Maximum working voltage = 18.0 V)

GAS DISCHARGE READOUT



**A filament pre-warm resistor is recommended to reduce filament thermal shock and increase the effective cold resistance of the filament.

LIQUID CRYSTAL (LCD) READOUT



Direct DC drive of LCD's not recommended for life of LCD readouts.

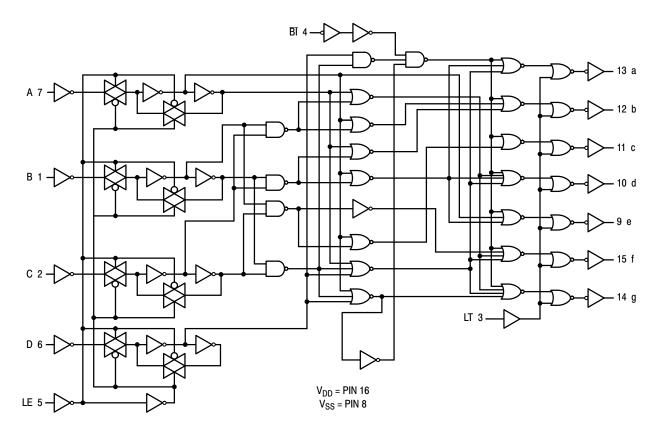


Figure 3. Logic Diagram

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14511BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14511BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14511BDWR2G	SO-16 WB (Pb-Free)	1000 / Tape & Reel
NLV14511BDWR2G*	SO-16 WB (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

MECHANICAL CASE OUTLINE



DATE 29 DEC 2006

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- THE NOTION AND TOLETANOING FER ANSI'Y 14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- PHOI HUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR PROTRUSION

 SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D

 DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
C	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050 BSC			
J	0.19	0.25	0.008	0.009		
K	0.10	0.25	0.004	0.009		
M	0°	7°	0°	7°		
P	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:			
PIN 1.	COLLECTOR	PIN 1.	CATHODE	PIN 1.	COLLECTOR, DYE #1	PIN 1.	COLLECTOR, DYE	#1	
2.	BASE	2.	ANODE	2.	BASE, #1	2.	COLLECTOR, #1		
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER, #1	3.	COLLECTOR, #2		
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2		
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3		
6.	BASE	6.	NO CONNECTION	6.	BASE, #2	6.	COLLECTOR, #3		
7.	COLLECTOR	7.	ANODE	7.	EMITTER, #2	7.	COLLECTOR, #4		
8.	COLLECTOR	8.	CATHODE	8.	COLLECTOR, #2	8.	COLLECTOR, #4		
9.	BASE	9.	CATHODE	9.	COLLECTOR, #3	9.	BASE, #4		
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4		
11.	NO CONNECTION	11.	NO CONNECTION	11.	EMITTER, #3	11.	BASE, #3		
12.	EMITTER	12.	CATHODE	12.	COLLECTOR, #3	12.	EMITTER, #3		
13.	BASE	13.	CATHODE	13.	COLLECTOR, #4	13.	BASE, #2	COL DEDING	FOOTPRINT
14.	COLLECTOR	14.	NO CONNECTION	14.	BASE, #4	14.	EMITTER, #2	SOLDERING	3 FOOTPRINT
15.	EMITTER	15.	ANODE	15.	EMITTER, #4	15.	BASE, #1		8X
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1		5.40 →
								7	,.40
STYLE 5:		STYLE 6:		STYLE 7:					16X 1.12 <
PIN 1.	DRAIN, DYE #1		CATHODE	PIN 1.	SOURCE N-CH				
2.	DRAIN, #1		CATHODE	2.	COMMON DRAIN (OUTPU	T)		. 1	16
3.	DRAIN, #2	3.		3.	COMMON DRAIN (OUTPU			↓ └── ·	" 🗀
4.	DRAIN, #2	4.	CATHODE	4.	GATE P-CH	•,		- —	
5.	DRAIN, #3	5.	CATHODE	5.	COMMON DRAIN (OUTPU	T)	16	5X T	
6.	DRAIN, #3	6.	CATHODE	6.	COMMON DRAIN (OUTPU		0.5	iii I	· —
7.	DRAIN, #4	7.	CATHODE	7.	COMMON DRAIN (OUTPU		0.0		
8.	DRAIN, #4	8.	CATHODE	8.	SOURCE P-CH	,			
9.	GATE, #4	9.	ANODE	9.	SOURCE P-CH				
10.	SOURCE, #4	10.	ANODE	10.	COMMON DRAIN (OUTPU	T)			
11.	GATE, #3	11.	ANODE	11.	COMMON DRAIN (OUTPU	T)			
12.	SOURCE, #3	12.	ANODE	12.	COMMON DRAIN (OUTPU	T)			
13.	GATE, #2	13.	ANODE	13.	GATE N-CH				
14.	SOURCE, #2	14.	ANODE	14.	COMMON DRAIN (OUTPU	T)			— V PITCH
15.	GATE, #1	15.	ANODE	15.	COMMON DRAIN (OUTPU				<u> </u>
16.	SOURCE, #1	16.	ANODE	16.	SOURCE N-CH				
								8	9 + - + -
								 •	_ - _
									DIMENSIONS: MILLIMETERS
									DIMENSIONS: MILLIMETERS

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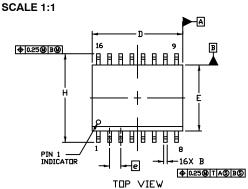


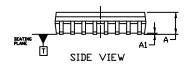


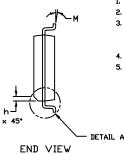
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DATE 08 OCT 2021









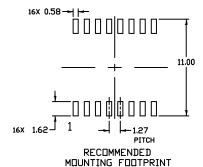


DETAIL A

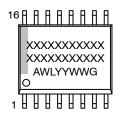
NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- MAXIMUM MOLD PROTRUSION OR FLASH TO BE 0.15 PER SIDE.

	MILLIMETERS			
DIM	MIN.	MAX.		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	10.15	10.45		
E	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.53 REF			
١	0.50	0.90		
М	0*	7*		



GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot YY = Year ww = Work Week G = Pb-Free Package

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